

Product Summary

BV _{DSS}	R _{DS(on)} Max	I _D Max T _C = +25°C
80V	7.0mΩ @ V _{GS} = 10V	95A
	11mΩ @ V _{GS} = 4.5V	75A

Description

This new generation MOSFET features low on-resistance and fast switching, making it ideal for high-efficiency power management applications.

Applications

- Power Management Functions
- DC-DC Converters
- Backlighting

Features

- 100% Unclamped Inductive Switching (UIS) Test in Production – Ensures More Reliable and Robust End Application
- Low R_{DS(on)} – Minimizes Power Losses
- Low Q_g – Minimizes Switching Losses
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](mailto:contact_us) or your local Diodes representative. <https://www.diodes.com/quality/product-definitions/>**

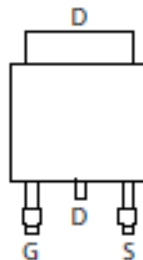
Mechanical Data

- Package: TO252
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.33 grams (Approximate)

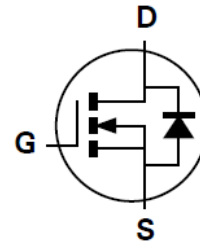
TO252 (DPAK)



Top View



Pin Out
Top View



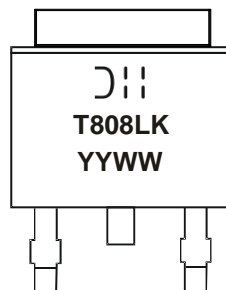
Equivalent Circuit

Ordering Information

Part Number	Package	Packing	
		Qty.	Carrier
DMT8008LK3-13	TO252 (DPAK)	2,500	Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



DII = Manufacturer's Marking
 T808LK = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Last Two Digits of Year (ex: 21 = 2021)
 WW = Week Code (01 to 53)

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	80	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current, $V_{GS} = 10\text{V}$	I_D	$T_C = +25^\circ\text{C}$ 95	A
		$T_C = +70^\circ\text{C}$ 76	
Pulsed Drain Current (10 μs Pulse, Duty Cycle = 1%)	I_{DM}	380	A
Maximum Continuous Body Diode Forward Current (Note 6)	I_S	95	A
Pulsed Body Diode Forward Current (10 μs Pulse, Duty Cycle = 1%)	I_{SM}	380	A
Avalanche Current, $L = 0.1\text{mH}$	I_{AS}	23	A
Avalanche Energy, $L = 0.1\text{mH}$	E_{AS}	26.5	mJ

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P_D	1.7	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	71	$^\circ\text{C/W}$
Total Power Dissipation (Note 6)	P_D	3	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	45	$^\circ\text{C/W}$
Thermal Resistance, Junction to Case	$R_{\theta JC}$	1.1	
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	80	—	—	V	$V_{GS} = 0V, I_D = 1mA$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	μA	$V_{DS} = 64V, V_{GS} = 0V$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(th)}$	1.3	—	2.8	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
Static Drain-Source On-Resistance	$R_{DS(on)}$	—	5.6	7.0	m Ω	$V_{GS} = 10V, I_D = 14A$
		—	7.9	11		$V_{GS} = 4.5V, I_D = 12A$
Diode Forward Voltage	V_{SD}	—	0.8	1.2	V	$V_{GS} = 0V, I_S = 20A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	2345	—	pF	$V_{DS} = 40V, V_{GS} = 0V,$ $f = 1MHz$
Output Capacitance	C_{oss}	—	842	—		
Reverse Transfer Capacitance	C_{rss}	—	52	—		
Gate Resistance	R_g	—	1.7	—	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$
Total Gate Charge ($V_{GS} = 4.5V$)	Q_g	—	21.7	—	nC	$V_{DD} = 40V, I_D = 2A$
Total Gate Charge ($V_{GS} = 10V$)	Q_g	—	41.2	—		
Gate-Source Charge	Q_{gs}	—	5.0	—		
Gate-Drain Charge	Q_{gd}	—	10.6	—		
Turn-On Delay Time	$t_{D(on)}$	—	5.8	—	ns	$V_{DD} = 40V, V_{GS} = 10V,$ $I_D = 2A, R_G = 1.6\Omega$
Turn-On Rise Time	t_R	—	5.4	—		
Turn-Off Delay Time	$t_{D(off)}$	—	24.5	—		
Turn-Off Fall Time	t_F	—	43.2	—		
Body Diode Reverse Recovery Time	t_{RR}	—	61	—	ns	$I_F = 2A, di/dt = 100A/\mu s$
Body Diode Reverse Recovery Charge	Q_{RR}	—	181	—	nC	

Notes: 7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.

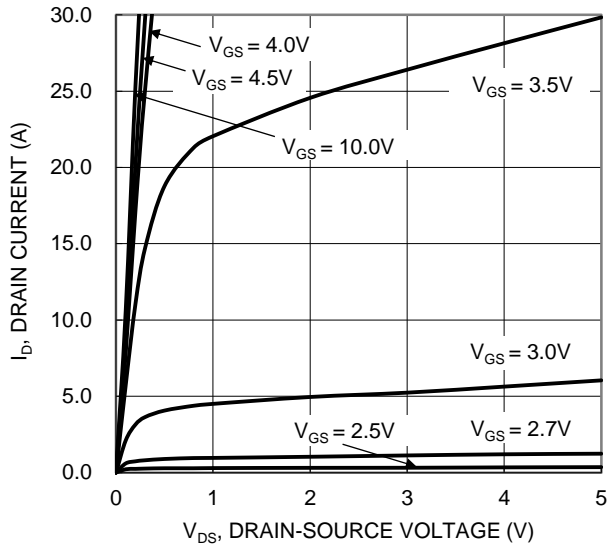


Figure 1. Typical Output Characteristic

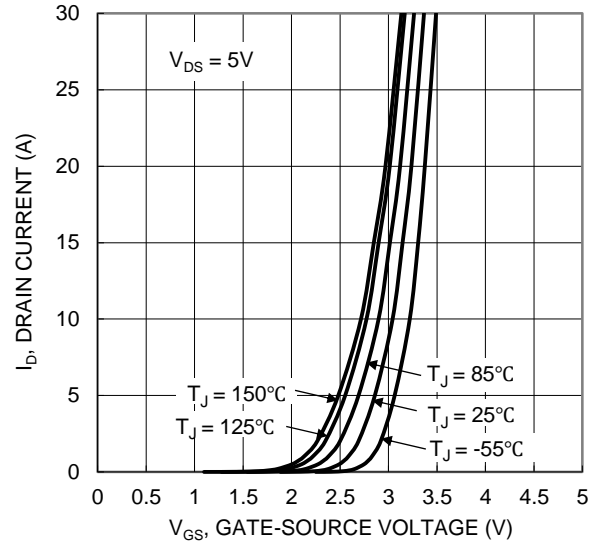


Figure 2. Typical Transfer Characteristic

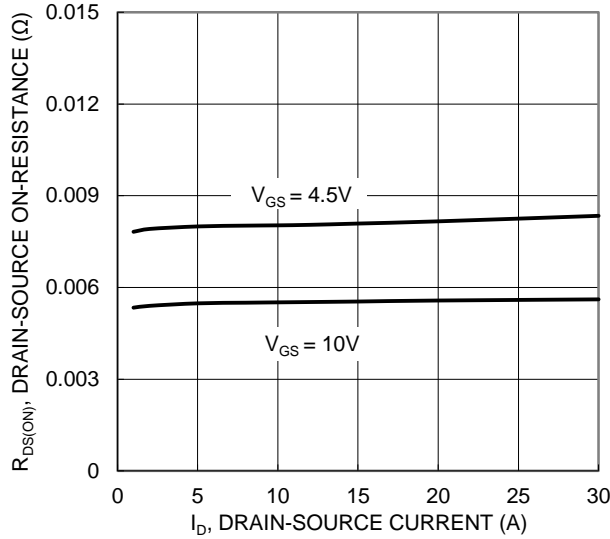


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

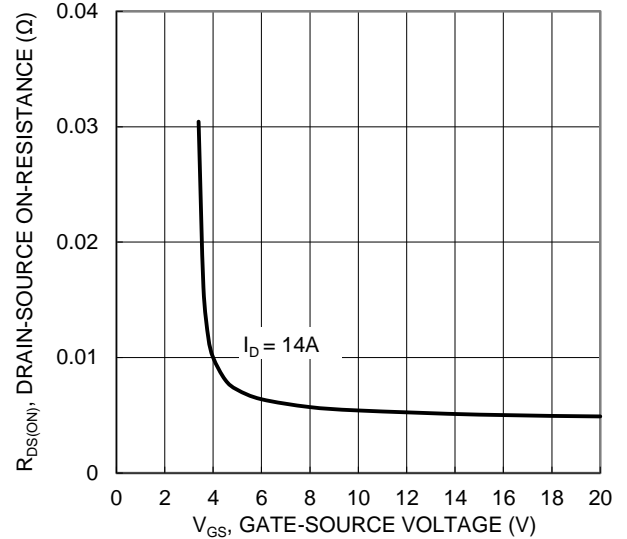


Figure 4. Typical Transfer Characteristic

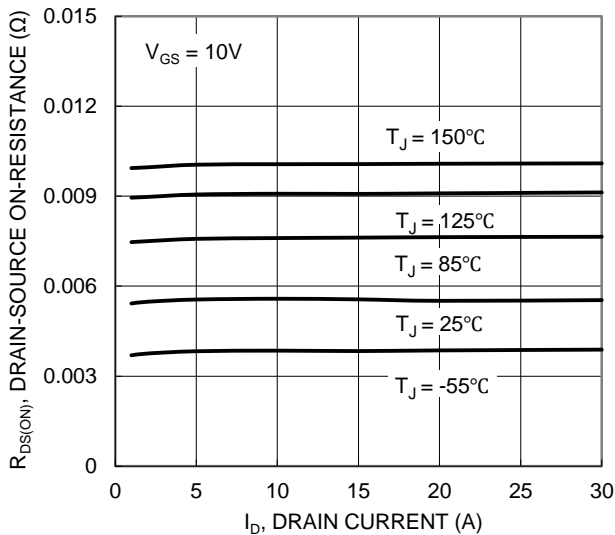


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

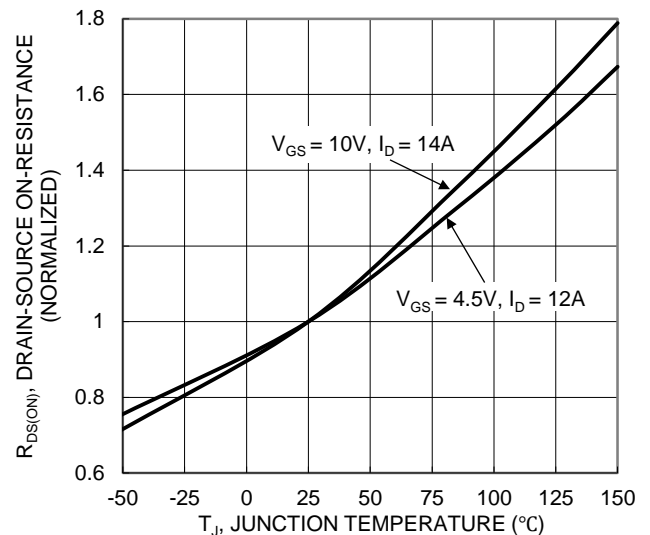


Figure 6. On-Resistance Variation with Junction Temperature

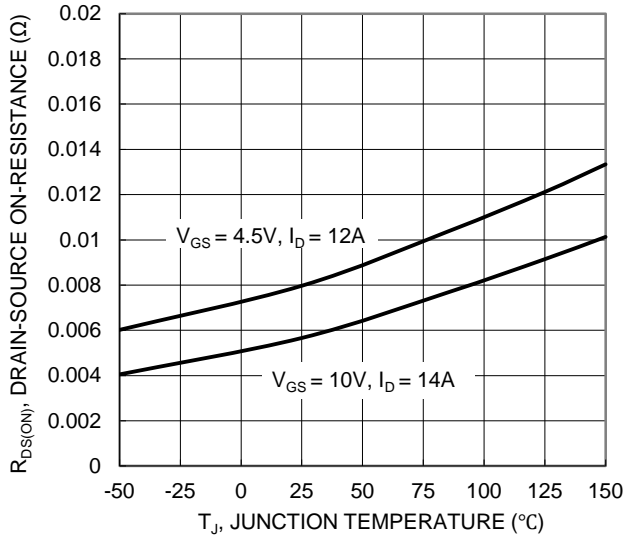


Figure 7. On-Resistance Variation with Temperature

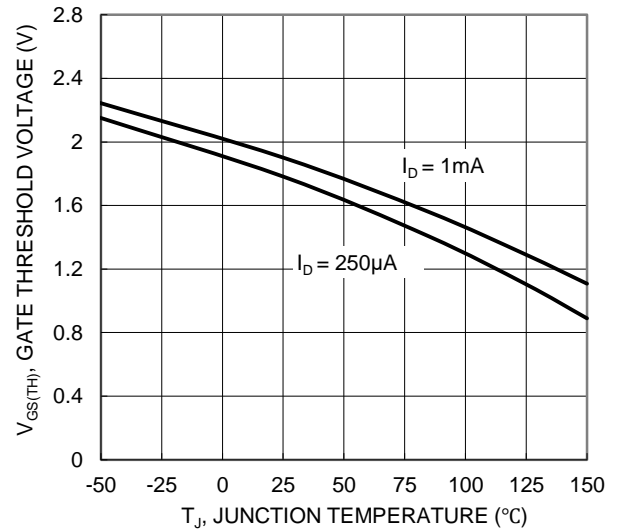


Figure 8. Gate Threshold Variation vs. Temperature

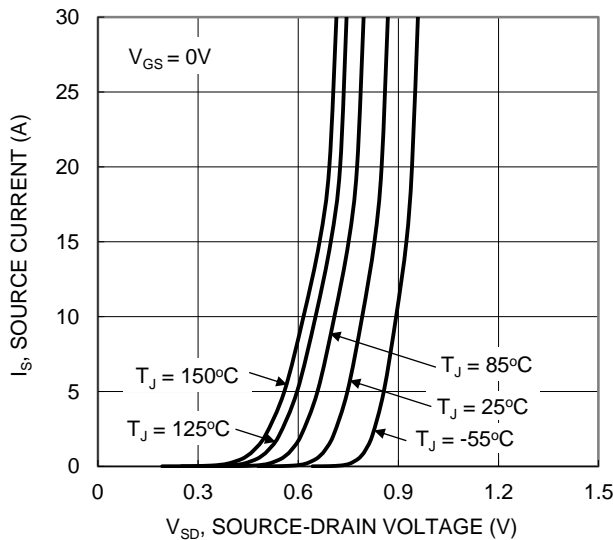


Figure 9. Diode Forward Voltage vs. Current

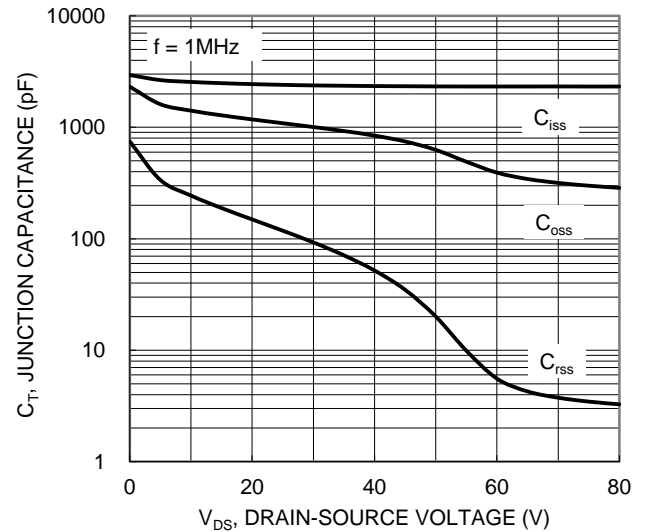


Figure 10. Typical Junction Capacitance

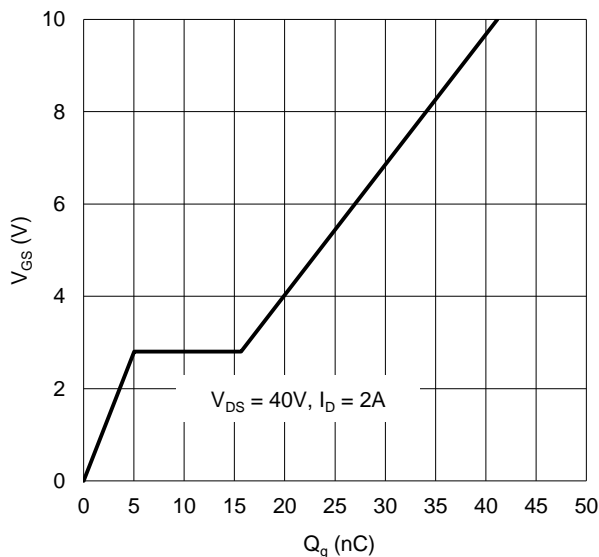


Figure 11. Gate Charge

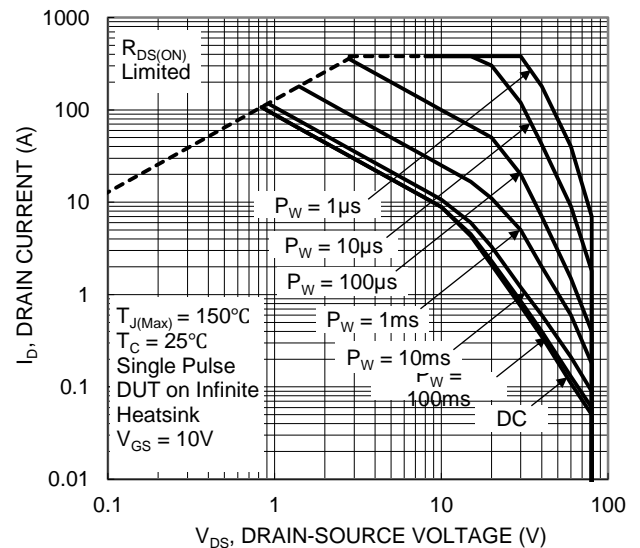


Figure 12. SOA, Safe Operation Area

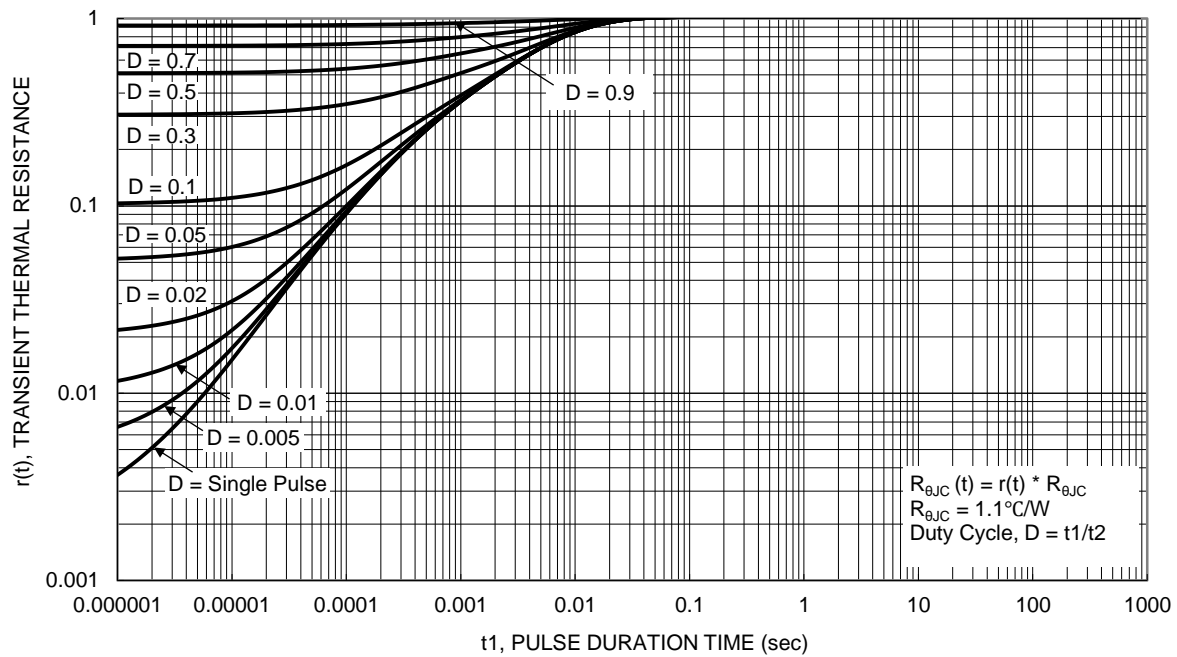
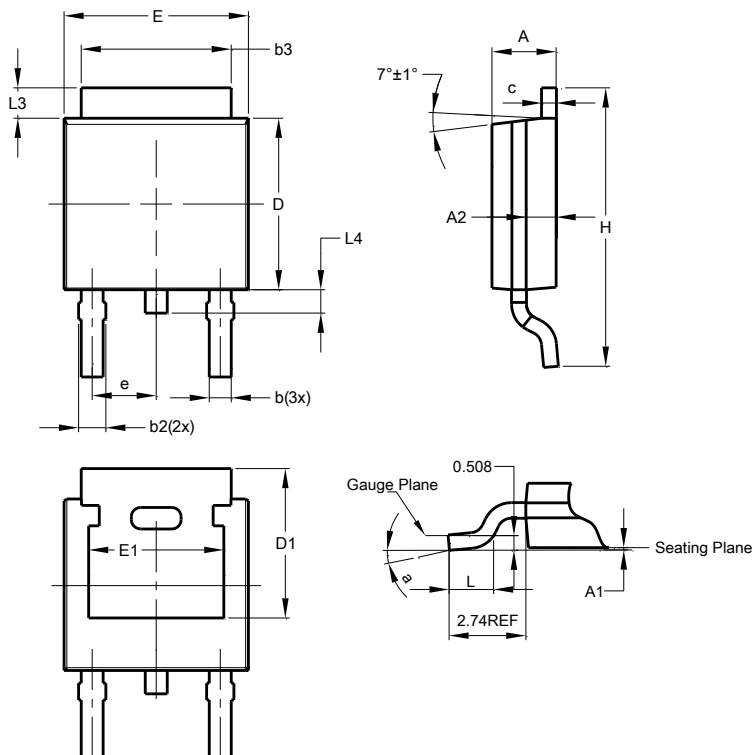


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

TO252 (DPAK)

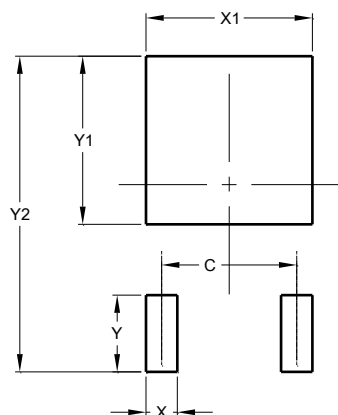


TO252 (DPAK)			
Dim	Min	Max	Typ
A	2.19	2.39	2.29
A1	0.00	0.13	0.08
A2	0.97	1.17	1.07
b	0.64	0.88	0.783
b2	0.76	1.14	0.95
b3	5.21	5.46	5.33
c	0.45	0.58	0.531
D	6.00	6.20	6.10
D1	5.21	—	—
e	—	—	2.286
E	6.45	6.70	6.58
E1	4.32	—	—
H	9.40	10.41	9.91
L	1.40	1.78	1.59
L3	0.88	1.27	1.08
L4	0.64	1.02	0.83
a	0°	10°	—
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

TO252 (DPAK)



Dimensions	Value (in mm)
C	4.572
X	1.060
X1	5.632
Y	2.600
Y1	5.700
Y2	10.700

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